

# Material Composition Specification

SOT-143 Case

Available with Pb(lead)-free plating\*



Device average mass ..... **9.4mg**

Fluctuation margin ..... **+/-10%**

Device part	Substance	mass (mg)
active device	doped Si	0.38
bond wire	Au	0.02
leadframe	FeNi42 (Alloy 42)	1.95
leadframe plating	Ag	0.07
	Cu	1.66
*plating	SnPb10 or Sn (100% tin, Pb-free)	0.10 0.10
encapsulation	partially brominated epoxy -silica -resin (phenolix and epoxy) < 20% -Sb <sub>2</sub> O <sub>3</sub> < 1.0% -carbon < 1.0	5.21
<b>Packing material (per 7" reel)</b>		<b>(g)</b>
reel	polystyrene	65
carrier tape	polycarbonate	31
cover tape	polyester	4.4
box	cardboard	172
bubble wrap	polyethylene, ethoxylated fatty amine	34
label/tape	paper	28

\*Specify Lead-free when ordering 100% tin (Pb-free) plating option.